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10084923  
03/01/02

PATENT NUMBER and  
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10084923	03/01/2002	751 438	751	2842	Williams

**\*\*APPLICANTS:** Taniguchi Osamu; Miyashita Tomoko; Yamagishi Yasuo; Omote Koji;  
Imanaka Yoshihiko;

**\*\*CONTINUING DATA VERIFIED:**

NONE WB

**\*\* FOREIGN APPLICATIONS VERIFIED:**

JAPAN 2001-262359 08/30/2001 WB

PG-PUB DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed ☒ yes ☐ no  
35 USC 119 conditions met ☒ yes ☐ no  
Verified and Acknowledged Examiners's initials WB

ATTORNEY DOCKET NO

020255

**TITLE :** Thin-film circuit substrate and manufacturing method thereof, and a via formed substrate and manufacturing method thereof

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436 (Rev. 12-94)

<b>NOTICE OF ALLOWANCE MAILED</b>		<b>CLAIMS ALLOWED</b>	
		Total Claims	Print Claim for O.G.
<b>ISSUE FEE</b>			
Amount Due	Date Paid		
		<b>PREPARED FOR ISSUE</b>	
<input type="checkbox"/> <b>TERMINAL DISCLAIMER</b>		<b>Application Examiner</b>	
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